F	1 2	3	4		5		6		
					RECOM	IENDATION FOR	SOLDER PROCE	SSING	
4	harming har-flex THR straight female connector					Solder paste recommendation			
						The har-flex connectors are solderable with established lead-f			
	GENERAL INFORMATION	PCB pad plating							
Ī	No. of contacts	The har-flex connectors are solderable on lead-free pad surface							
	Contact spacing	1							
	Test Voltage		Stencil re	ecommendation					
	Contact resistance		deposition has to						
	Insulation resistance	≥ 10x10^9Ω				Ideally, the solder deposition has the same length-to-width ratio The size of the solder stencil apertures is depending on the thic			
	Working current acc. to IEC 60512, at 70°C, 80% deratingsee derating diagramWorking temperature range-55°C +125°C					In general, a thinner stencils will need larger apertures to result The minimum required solder paste volume for the signal pins i For example, this can be achieved with the following stencil dat			
3									
	Termination technology		For example, this can be achieved with the following stence da						
	Reflow processing temperature	min. 150s >217°C					r		
	(acc. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	min. 30s>240°C	· · · ·		- F			Signa	
	Clearance & creepage distance	0,4mm min.				Stencil thickness	PCB pad size	proposal ste	
	Insertion force (depending on mating connector)	approximately 0,5N/contact				150 µm	1,1 x 0,8 mm	0,99	
	Withdrawal force (depending on mating connector)     approximately 0,5N/contact							Hold-o	
	Mating cycles	PL1 : 500 mating cycles PL2 : 250 mating cycles			[	Stencil thickness	PCB pad size	proposal ste	
.	RoHS - compliant	Yes			-	150 µm	Ø0,8 mm		
•	Leadfree	Yes	· · ·			150 µm	<i>\ϕ</i> 0,0 mm	Ş	
	Working voltage acc. to to IEC 60664-1 100V / 150V (depending on installation category)					If a stencil with lower thickness shall be used, please insure th			
	UL file acc. UL 1977					erture. Depending o	on the PCB design	, the solder dep	
	UL file acc. CSA-C22.2 (for Canada) ECBT8.E102079					ring solder paste p CB pad about 10%			
	PSL level acc. ECA/IPC/JEDEC J-STD-075	PSL R0			than the PCB pad about 10% or 25µm encircliing.				
	MSL level acc. ECA/IPC/JEDEC J-STD-020D	MSL 1				Coplanarity of contacts All connectors are tested for coplanarity of contacts and are in			
İ	INSULATOR MATERIAL				copiananty of cor				
	Material	LCP (liquid crystalline polym	er)		Performa	ance level			
ן נ	Color	Black UL94-V0			<ul> <li>Performance level 1 (recommended for majority of applications</li> <li>Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) usi</li> <li>Measurement of contact resistance. The remaining 250 mating and visual inspection.</li> </ul>				
	UL classification								
	Material group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)							
r						Visual inspection. No abrasion of the contact finish through to t			
┦		-	Part number definition : 15 2						
	Contact material	Copper alloy			Performar	nce level 2			
	Plating termination zone Plating contact sliding side	Sn Au over PdNi (acc. to Performance level)			Initial 125 mating cycles, 4 days gas test (25°C / 75% r.h.) usin				
			Measurement of contact resistance. The remaining 125 mating and visual inspection. Visual inspection. No abrasion of the contact finish through to the						
	DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity)								
	The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals. The current capacity curve is valid for continuous, non	Ectrical load [A]			Part number definition : 15 6 Performance level S4 Defined contact surface of min. 0,06 µm Au over 0,7+0,2µm Po Part number definition : 15 5				
	interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.					All Dimensions in m Original Size DIN A	3 1:1	size tol.	
F		Ш 1	H I		MARTING -	All rights reserved	— 7HUANGI	Inspected by LUOK	
	Control and test procedures according to DIN IEC 60512-5 derating curve at Imax*0,8 (IEC 60512-5-2)	0 0 10 20 30 40 50 60 70 80 90 100 110 120 130 € Temperature [°C]			Department EC PD - CN		Title	THR straight	
	ueraling curve at initax 0,0 (IEC 00012-0-2)				HARTING Elec	tronics GmbH			
				<b>I</b>	D-32339 Espe	lkamp	Type DS	Number 1521211	
	1 2	3	4		5		6		

7		8										
			]									
ad-free SAC / SnNi solde	r hut	also loadod	solder e a SnDh10	A								
au-IIEE SAC / SHINI SOIDE	n DUL		Soluel e.y. 311PD40									
urfaces like HAL NiAu Ir	nmor	sion Sn										
urfaces like HAL, NiAu, Immersion Sn.												
he contact solder tines. ratio and center point like the PCB pads.												
thickness of the stencil.												
esult in the required volume of solder paste.												
ins is 0,094mm <sup>3</sup> , for the hold down it is 1,179mm <sup>3</sup> .												
Signal pins												
stencil aperture size	calc	calculated solder paste volume										
0,99 x 0,72 mm		0,107 mm <sup>3</sup>										
old-downs												
stencil aperture size	calc	ulated solder	paste volume									
$\emptyset$ 2,3 mm	calc		9 mm <sup>3</sup>									
Ψ <b>2</b> ,3 mm		1,173	9 11111	C								
e the minimum required s	older	paste volum	e by enlarging the									
depostion may protrude the PCB pads. But to achieve a good												
ing interval of the stencil, the aperture should be smaller												
e in the range of 6 pin to 80 pin: ≤ 0,1mm												
82 pin to 100 pin: $\leq$ 0,15mm												
		-										
ions)												
) using H2S 10 ppb, NO2 ting cycles are subject to												
	mea											
to the base material. No functional impairment.												
using H2S 10 ppb, NO2 2 ting cycles are subject to												
ting cycles are subject to measurement of contact resistance												
to the base material. No functional impairment.												
n PdNi												
	Ref.			┥凵								
	Sub.			+								
y Standardisation	Date		State	1								
HOFFMANN	2016-	11-29	Final Release									
ht female												
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